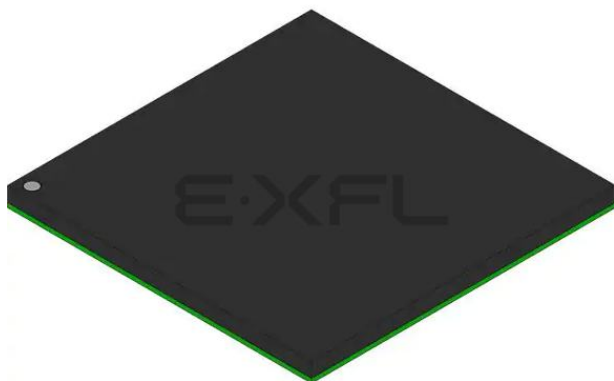




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Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Active
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	66MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (1), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc855tzq66d4

2 Features

The following list summarizes the key MPC860 features:

- Embedded single-issue, 32-bit core (implementing the Power Architecture technology) with thirty-two 32-bit general-purpose registers (GPRs)
 - The core performs branch prediction with conditional prefetch without conditional execution.
 - 4- or 8-Kbyte data cache and 4- or 16-Kbyte instruction cache (see [Table 1](#))
 - 16-Kbyte instruction caches are four-way, set-associative with 256 sets; 4-Kbyte instruction caches are two-way, set-associative with 128 sets.
 - 8-Kbyte data caches are two-way, set-associative with 256 sets; 4-Kbyte data caches are two-way, set-associative with 128 sets.
 - Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks.
 - Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
 - MMUs with 32-entry TLB, fully-associative instruction, and data TLBs
 - MMUs support multiple page sizes of 4-, 16-, and 512-Kbytes, and 8-Mbytes; 16 virtual address spaces and 16 protection groups
 - Advanced on-chip-emulation debug mode
- Up to 32-bit data bus (dynamic bus sizing for 8, 16, and 32 bits)
- 32 address lines
- Operates at up to 80 MHz
- Memory controller (eight banks)
 - Contains complete dynamic RAM (DRAM) controller
 - Each bank can be a chip select or $\overline{\text{RAS}}$ to support a DRAM bank.
 - Up to 15 wait states programmable per memory bank
 - Glueless interface to DRAM, SIMMS, SRAM, EPROM, Flash EPROM, and other memory devices
 - DRAM controller programmable to support most size and speed memory interfaces
 - Four $\overline{\text{CAS}}$ lines, four $\overline{\text{WE}}$ lines, and one $\overline{\text{OE}}$ line
 - Boot chip-select available at reset (options for 8-, 16-, or 32-bit memory)
 - Variable block sizes (32 Kbytes to 256 Mbytes)
 - Selectable write protection
 - On-chip bus arbitration logic
- General-purpose timers
 - Four 16-bit timers or two 32-bit timers
 - Gate mode can enable/disable counting
 - Interrupt can be masked on reference match and event capture.

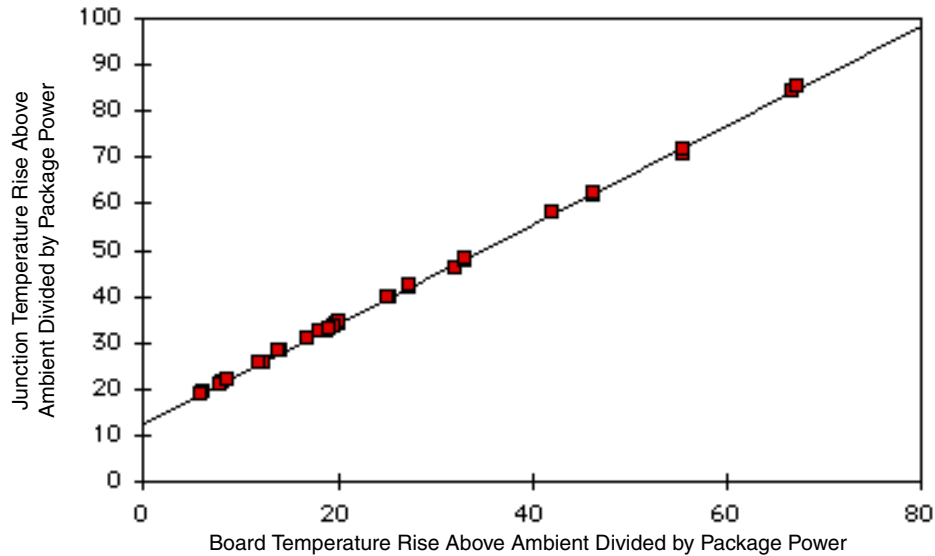


Figure 2. Effect of Board Temperature Rise on Thermal Behavior

If the board temperature is known, an estimate of the junction temperature in the environment can be made using the following equation:

$$T_J = T_B + (R_{\theta JB} \times P_D)$$

where:

$R_{\theta JB}$ = junction-to-board thermal resistance ($^{\circ}\text{C}/\text{W}$)

T_B = board temperature ($^{\circ}\text{C}$)

P_D = power dissipation in package

If the board temperature is known and the heat loss from the package case to the air can be ignored, acceptable predictions of junction temperature can be made. For this method to work, the board and board mounting must be similar to the test board used to determine the junction-to-board thermal resistance, namely a 2s2p (board with a power and a ground plane) and by attaching the thermal balls to the ground plane.

7.4 Estimation Using Simulation

When the board temperature is not known, a thermal simulation of the application is needed. The simple two-resistor model can be used with the thermal simulation of the application [2], or a more accurate and complex model of the package can be used in the thermal simulation.

7.5 Experimental Determination

To determine the junction temperature of the device in the application after prototypes are available, the thermal characterization parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B29d	$\overline{WE}(0:3)$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, EBDF = 0	43.45	—	35.5	—	28.00	—	20.73	—	ns
B29e	$\overline{CS}$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	43.45	—	35.5	—	28.00	—	29.73	—	ns
B29f	$\overline{WE}(0:3)$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, EBDF = 1	8.86	—	6.88	—	5.00	—	3.18	—	ns
B29g	$\overline{CS}$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	8.86	—	6.88	—	5.00	—	3.18	—	ns
B29h	$\overline{WE}(0:3)$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B29i	$\overline{CS}$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B30	$\overline{CS}$, $\overline{WE}(0:3)$ negated to A(0:31), BADDR(28:30) invalid GPCM write access ⁸	5.58	—	4.25	—	3.00	—	1.79	—	ns
B30a	$\overline{WE}(0:3)$ negated to A(0:31), BADDR(28:30) invalid GPCM, write access, TRLX = 0, CSNT = 1, $\overline{CS}$ negated to A(0:31) invalid GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	13.15	—	10.50	—	8.00	—	5.58	—	ns
B30b	$\overline{WE}(0:3)$ negated to A(0:31), invalid GPCM BADDR(28:30) invalid GPCM write access, TRLX = 1, CSNT = 1. $\overline{CS}$ negated to A(0:31), Invalid GPCM, write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	43.45	—	35.50	—	28.00	—	20.73	—	ns
B30c	$\overline{WE}(0:3)$ negated to A(0:31), BADDR(28:30) invalid GPCM write access, TRLX = 0, CSNT = 1. $\overline{CS}$ negated to A(0:31) invalid GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, ACS = 11, EBDF = 1	8.36	—	6.38	—	4.50	—	2.68	—	ns
B30d	$\overline{WE}(0:3)$ negated to A(0:31), BADDR(28:30) invalid GPCM write access, TRLX = 1, CSNT = 1. $\overline{CS}$ negated to A(0:31) invalid GPCM write access TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B31	CLKOUT falling edge to $\overline{CS}$ valid—as requested by control bit CST4 in the corresponding word in UPM	1.50	6.00	1.50	6.00	1.50	6.00	1.50	6.00	ns

Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B35	A(0:31), BADDR(28:30) to $\overline{CS}$ valid—as requested by control bit BST4 in the corresponding word in UPM	5.58	—	4.25	—	3.00	—	1.79	—	ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to $\overline{BS}$ valid—as requested by control bit BST1 in the corresponding word in UPM	13.15	—	10.50	—	8.00	—	5.58	—	ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to $\overline{BS}$ valid—as requested by control bit BST2 in the corresponding word in UPM	20.73	—	16.75	—	13.00	—	9.36	—	ns
B36	A(0:31), BADDR(28:30), and D(0:31) to $\overline{GPL}$ valid—as requested by control bit GxT4 in the corresponding word in UPM	5.58	—	4.25	—	3.00	—	1.79	—	ns
B37	UPWAIT valid to CLKOUT falling edge ⁹	6.00	—	6.00	—	6.00	—	6.00	—	ns
B38	CLKOUT falling edge to UPWAIT valid ⁹	1.00	—	1.00	—	1.00	—	1.00	—	ns
B39	$\overline{AS}$ valid to CLKOUT rising edge ¹⁰	7.00	—	7.00	—	7.00	—	7.00	—	ns
B40	A(0:31), TSIZ(0:1), RD/ $\overline{WR}$, $\overline{BURST}$, valid to CLKOUT rising edge	7.00	—	7.00	—	7.00	—	7.00	—	ns
B41	$\overline{TS}$ valid to CLKOUT rising edge (setup time)	7.00	—	7.00	—	7.00	—	7.00	—	ns
B42	CLKOUT rising edge to $\overline{TS}$ valid (hold time)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B43	$\overline{AS}$ negation to memory controller signals negation	—	TBD	—	TBD	—	TBD	—	TBD	ns

¹ Phase and frequency jitter performance results are only valid if the input jitter is less than the prescribed value.

² If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time) then the maximum allowed jitter on EXTAL can be up to 2%.

³ The timings specified in B4 and B5 are based on full strength clock.

⁴ The timing for $\overline{BR}$ output is relevant when the MPC860 is selected to work with external bus arbiter. The timing for $\overline{BG}$ output is relevant when the MPC860 is selected to work with internal bus arbiter.

⁵ The timing required for $\overline{BR}$ input is relevant when the MPC860 is selected to work with internal bus arbiter. The timing for $\overline{BG}$ input is relevant when the MPC860 is selected to work with external bus arbiter.

⁶ The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of the CLKOUT in which the $\overline{TA}$ input signal is asserted.

⁷ The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of the CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

⁸ The timing B30 refers to $\overline{CS}$ when ACS = 00 and to $\overline{WE}$ (0:3) when CSNT = 0.

⁹ The signal UPWAIT is considered asynchronous to the CLKOUT and synchronized internally. The timings specified in B37 and B38 are specified to enable the freeze of the UPM output signals as described in [Figure 18](#).

¹⁰ The $\overline{AS}$ signal is considered asynchronous to the CLKOUT. The timing B39 is specified in order to allow the behavior specified in [Figure 21](#).

Figure 7 provides the timing for the synchronous input signals.

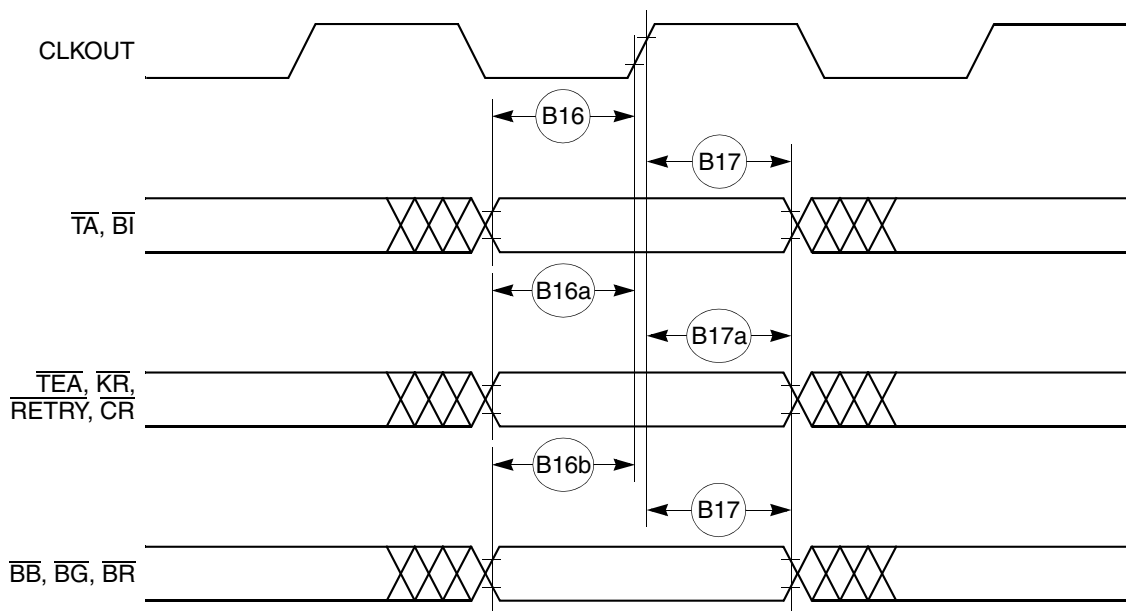


Figure 7. Synchronous Input Signals Timing

Figure 8 provides normal case timing for input data. It also applies to normal read accesses under the control of the UPM in the memory controller.

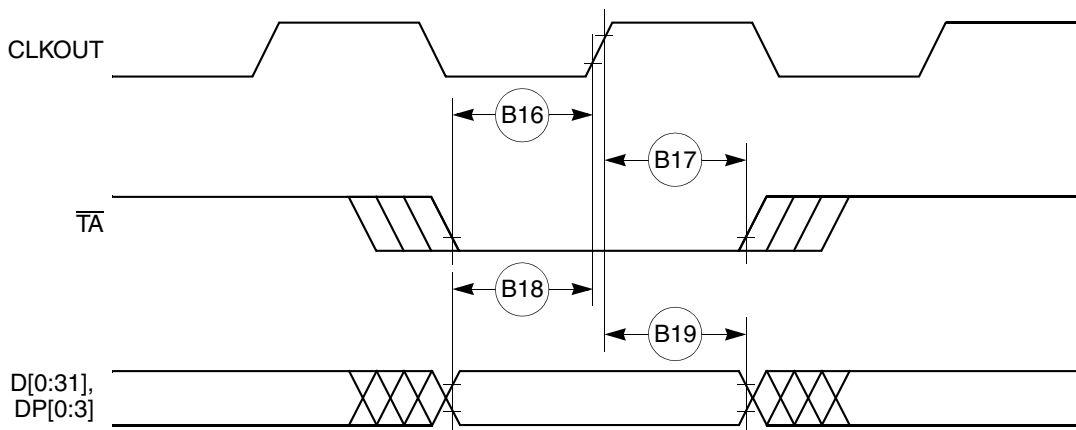


Figure 8. Input Data Timing in Normal Case

Figure 18 provides the timing for the asynchronous asserted UPWAIT signal controlled by the UPM.

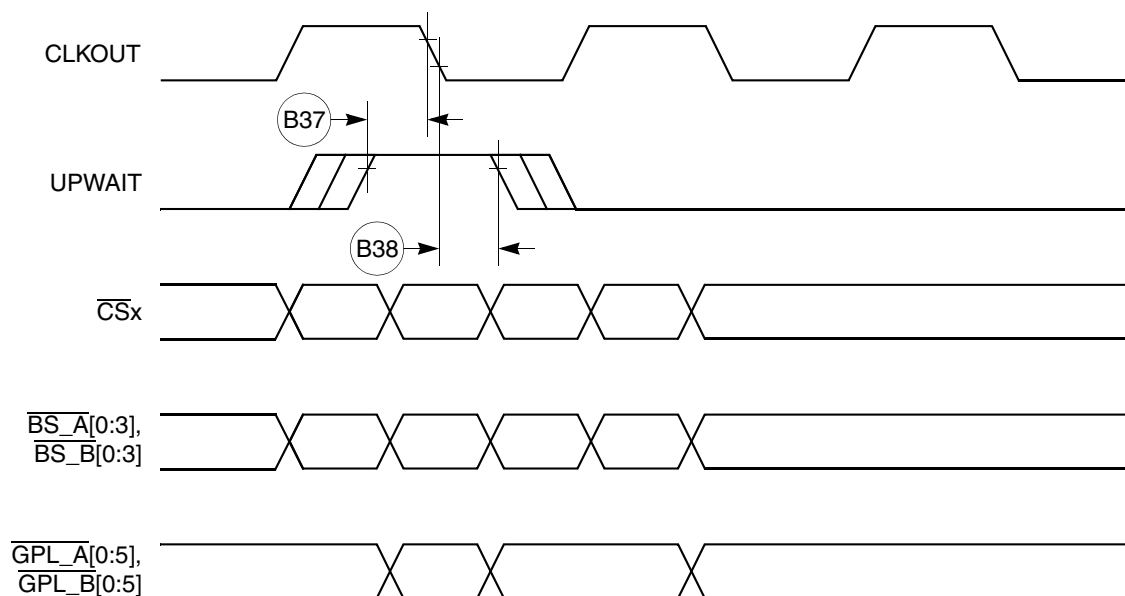


Figure 18. Asynchronous UPWAIT Asserted Detection in UPM Handled Cycles Timing

Figure 19 provides the timing for the asynchronous negated UPWAIT signal controlled by the UPM.

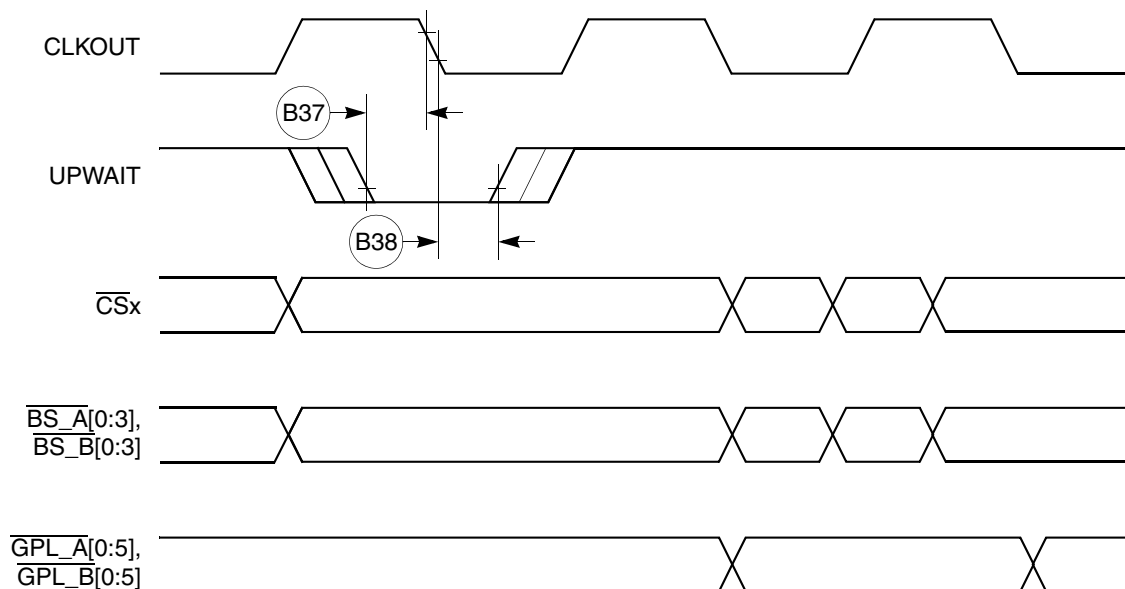


Figure 19. Asynchronous UPWAIT Negated Detection in UPM Handled Cycles Timing

Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
P44	A(0:31), $\overline{\text{REG}}$ valid to PCMCIA Strobe asserted ¹	20.73	—	16.75	—	13.00	—	9.36	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation ¹	28.30	—	23.00	—	18.00	—	13.15	—	ns
P46	CLKOUT to $\overline{\text{REG}}$ valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to $\overline{\text{REG}}$ invalid	8.58	—	7.25	—	6.00	—	4.84	—	ns
P48	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ assert time	—	11.00		11.00	—	11.00	—	11.00	ns
P51	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	—	15.58		14.25	—	13.00	—	11.84	ns
P54	$\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negated to D(0:31) invalid ¹	5.58	—	4.25	—	3.00	—	1.79	—	ns
P55	$\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ valid to CLKOUT rising edge ¹	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to $\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ invalid ¹	2.00	—	2.00	—	2.00	—	2.00	—	ns

¹ PSST = 1. Otherwise add PSST times cycle time.

PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the $\overline{\text{WAITx}}$ signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The $\overline{\text{WAITx}}$ assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, “PCMCIA Interface,” in the *MPC860 PowerQUICC™ Family User's Manual*.

Table 12 shows the reset timing for the MPC860.

Table 12. Reset Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
R69	CLKOUT to $\overline{\text{HRESET}}$ high impedance	—	20.00	—	20.00	—	20.00	—	20.00	ns
R70	CLKOUT to $\overline{\text{SRESET}}$ high impedance	—	20.00	—	20.00	—	20.00	—	20.00	ns
R71	$\overline{\text{RSTCONF}}$ pulse width	515.15	—	425.00	—	340.00	—	257.58	—	ns
R72	—	—	—	—	—	—	—	—	—	
R73	Configuration data to $\overline{\text{HRESET}}$ rising edge setup time	504.55	—	425.00	—	350.00	—	277.27	—	ns
R74	Configuration data to $\overline{\text{RSTCONF}}$ rising edge setup time	350.00	—	350.00	—	350.00	—	350.00	—	ns
R75	Configuration data hold time after $\overline{\text{RSTCONF}}$ negation	0.00	—	0.00	—	0.00	—	0.00	—	ns
R76	Configuration data hold time after $\overline{\text{HRESET}}$ negation	0.00	—	0.00	—	0.00	—	0.00	—	ns
R77	$\overline{\text{HRESET}}$ and $\overline{\text{RSTCONF}}$ asserted to data out drive	—	25.00	—	25.00	—	25.00	—	25.00	ns
R78	$\overline{\text{RSTCONF}}$ negated to data out high impedance	—	25.00	—	25.00	—	25.00	—	25.00	ns
R79	CLKOUT of last rising edge before chip three-state $\overline{\text{HRESET}}$ to data out high impedance	—	25.00	—	25.00	—	25.00	—	25.00	ns
R80	DSDI, DSCK setup	90.91	—	75.00	—	60.00	—	45.45	—	ns
R81	DSDI, DSCK hold time	0.00	—	0.00	—	0.00	—	0.00	—	ns
R82	$\overline{\text{SRESET}}$ negated to CLKOUT rising edge for DSDI and DSCK sample	242.42	—	200.00	—	160.00	—	121.21	—	ns

Figure 32 shows the reset timing for the data bus configuration.

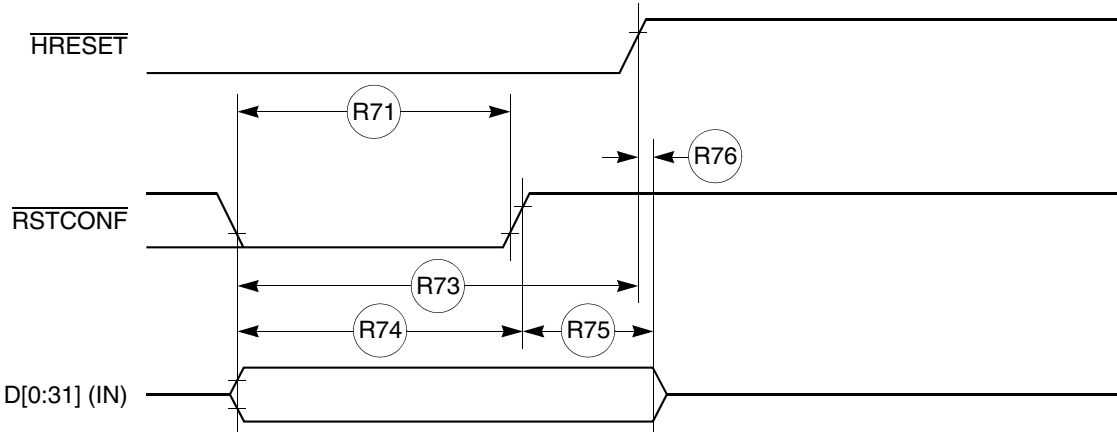


Figure 32. Reset Timing—Configuration from Data Bus

Figure 33 provides the reset timing for the data bus weak drive during configuration.

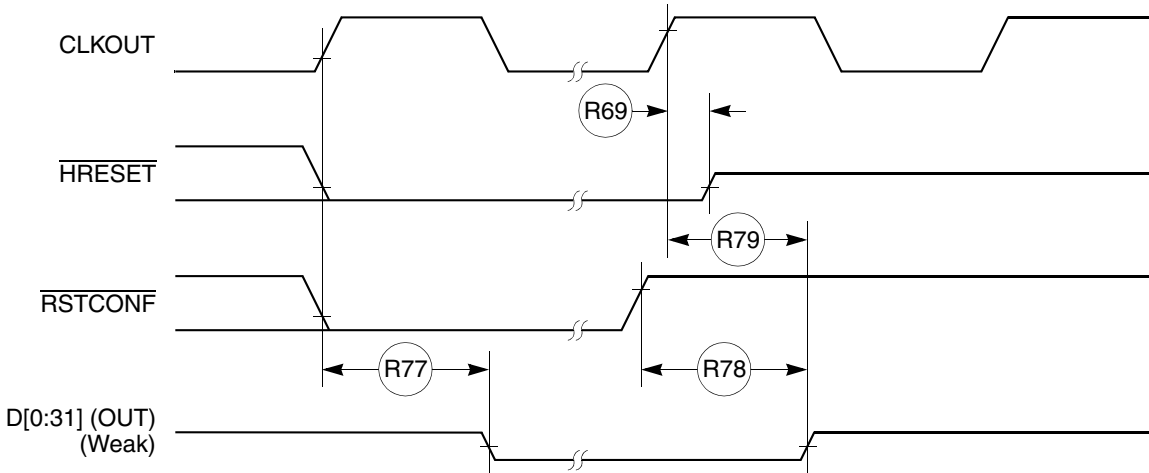


Figure 33. Reset Timing—Data Bus Weak Drive During Configuration

Figure 34 provides the reset timing for the debug port configuration.

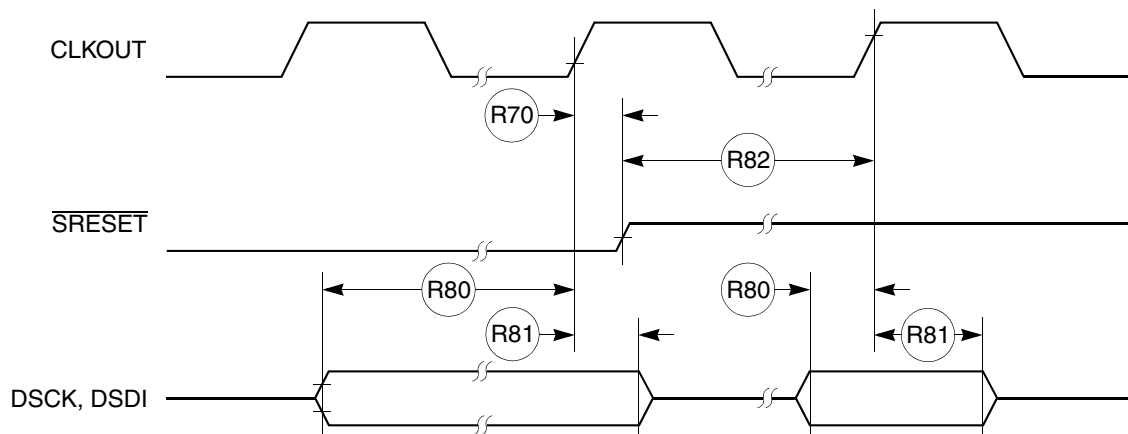


Figure 34. Reset Timing—Debug Port Configuration

10 IEEE 1149.1 Electrical Specifications

Table 13 provides the JTAG timings for the MPC860 shown in Figure 35 through Figure 38.

Table 13. JTAG Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
J82	TCK cycle time	100.00	—	ns
J83	TCK clock pulse width measured at 1.5 V	40.00	—	ns
J84	TCK rise and fall times	0.00	10.00	ns
J85	TMS, TDI data setup time	5.00	—	ns
J86	TMS, TDI data hold time	25.00	—	ns
J87	TCK low to TDO data valid	—	27.00	ns
J88	TCK low to TDO data invalid	0.00	—	ns
J89	TCK low to TDO high impedance	—	20.00	ns
J90	$\overline{\text{TRST}}$ assert time	100.00	—	ns
J91	$\overline{\text{TRST}}$ setup time to TCK low	40.00	—	ns
J92	TCK falling edge to output valid	—	50.00	ns
J93	TCK falling edge to output valid out of high impedance	—	50.00	ns
J94	TCK falling edge to output high impedance	—	50.00	ns
J95	Boundary scan input valid to TCK rising edge	50.00	—	ns
J96	TCK rising edge to boundary scan input invalid	50.00	—	ns

11 CPM Electrical Characteristics

This section provides the AC and DC electrical specifications for the communications processor module (CPM) of the MPC860.

11.1 PIP/PIO AC Electrical Specifications

Table 14 provides the PIP/PIO AC timings as shown in Figure 39 through Figure 43.

Table 14. PIP/PIO Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
21	Data-in setup time to STBI low	0	—	ns
22	Data-in hold time to STBI high	$2.5 - t_3^1$	—	CLK
23	STBI pulse width	1.5	—	CLK
24	STBO pulse width	1 CLK – 5 ns	—	ns
25	Data-out setup time to STBO low	2	—	CLK
26	Data-out hold time from STBO high	5	—	CLK
27	STBI low to STBO low (Rx interlock)	—	2	CLK
28	STBI low to STBO high (Tx interlock)	2	—	CLK
29	Data-in setup time to clock high	15	—	ns
30	Data-in hold time from clock high	7.5	—	ns
31	Clock low to data-out valid (CPU writes data, control, or direction)	—	25	ns

¹ t_3 = Specification 23.

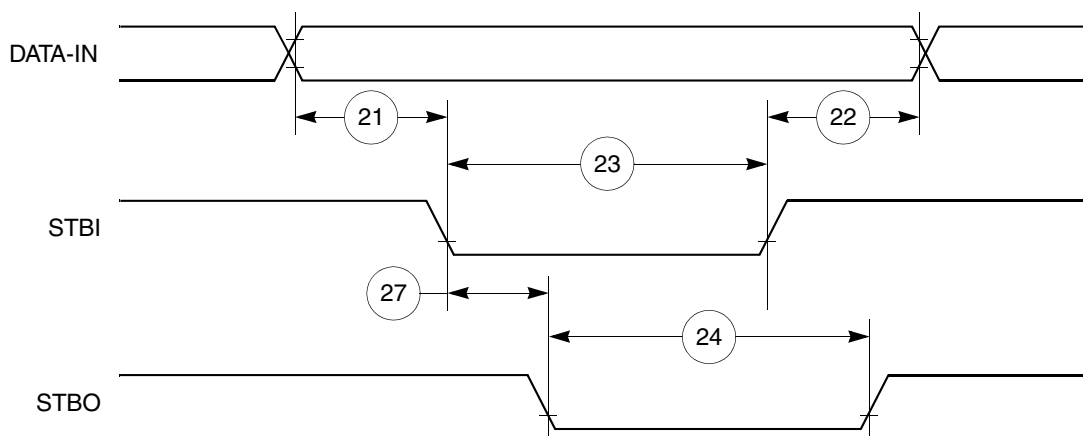


Figure 39. PIP Rx (Interlock Mode) Timing Diagram

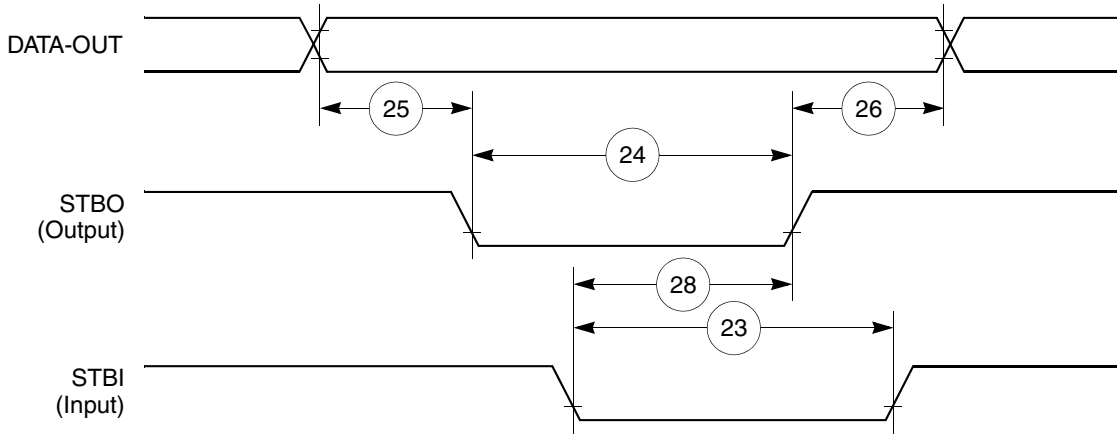


Figure 40. PIP Tx (Interlock Mode) Timing Diagram

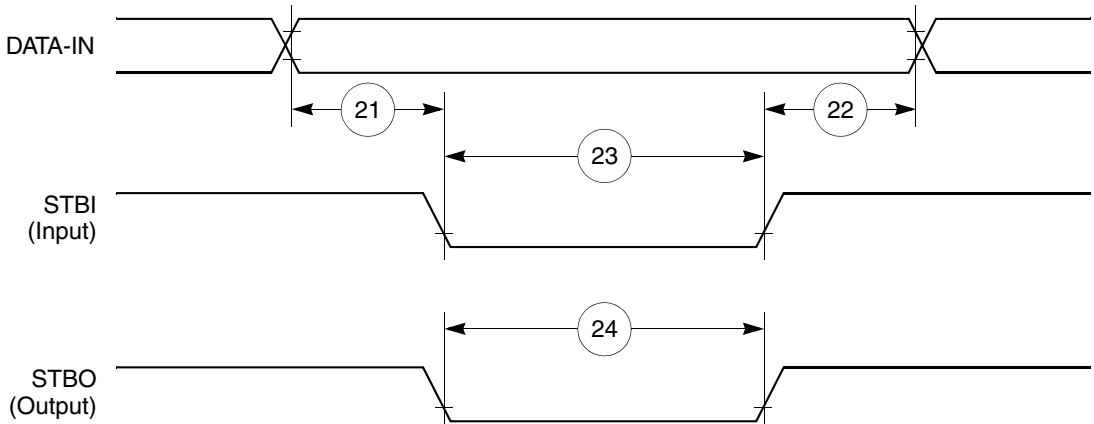


Figure 41. PIP Rx (Pulse Mode) Timing Diagram

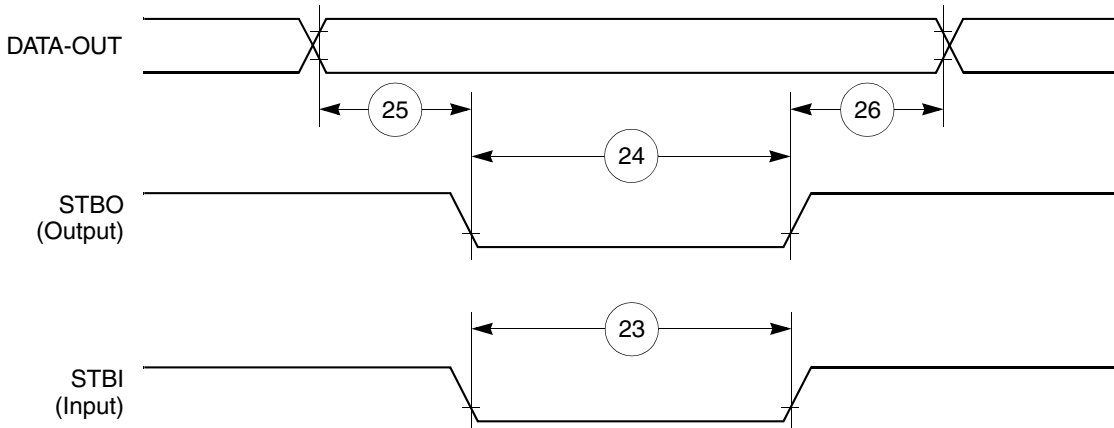


Figure 42. PIP TX (Pulse Mode) Timing Diagram

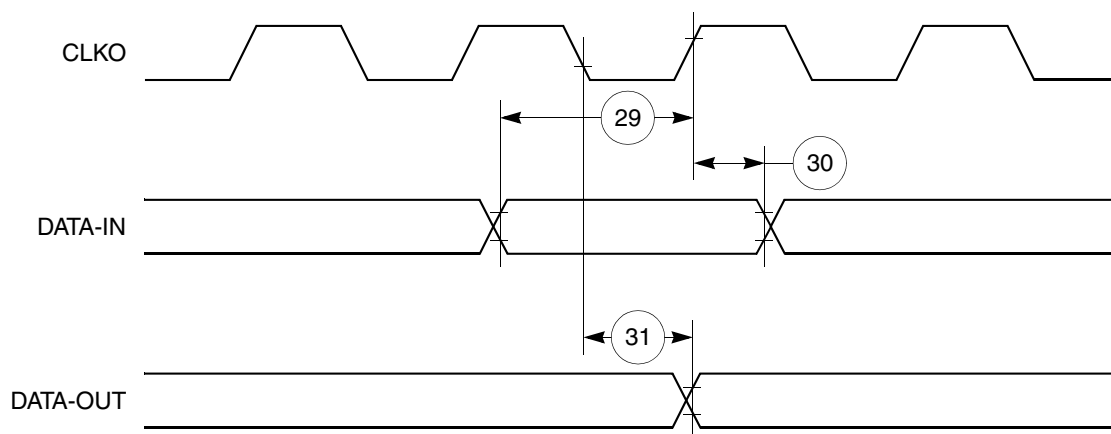


Figure 43. Parallel I/O Data-In/Data-Out Timing Diagram

11.2 Port C Interrupt AC Electrical Specifications

Table 15 provides the timings for port C interrupts.

Table 15. Port C Interrupt Timing

Num	Characteristic	$\geq 33.34 \text{ MHz}^1$		Unit
		Min	Max	
35	Port C interrupt pulse width low (edge-triggered mode)	55	—	ns
36	Port C interrupt minimum time between active edges	55	—	ns

¹ External bus frequency of greater than or equal to 33.34 MHz.

Figure 44 shows the port C interrupt detection timing.

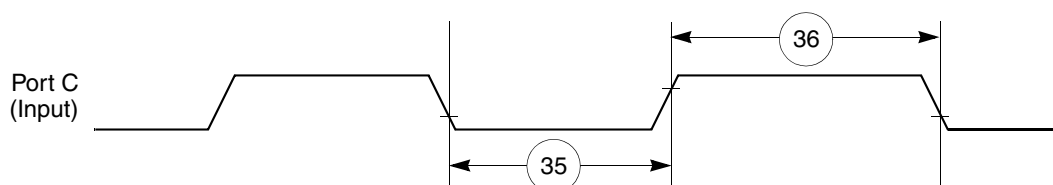


Figure 44. Port C Interrupt Detection Timing

11.3 IDMA Controller AC Electrical Specifications

Table 16 provides the IDMA controller timings as shown in Figure 45 through Figure 48.

Table 16. IDMA Controller Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
40	$\overline{\text{DREQ}}$ setup time to clock high	7	—	ns
41	$\overline{\text{DREQ}}$ hold time from clock high	3	—	ns

11.4 Baud Rate Generator AC Electrical Specifications

Table 17 provides the baud rate generator timings as shown in Figure 49.

Table 17. Baud Rate Generator Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
50	BRGO rise and fall time	—	10	ns
51	BRGO duty cycle	40	60	%
52	BRGO cycle	40	—	ns

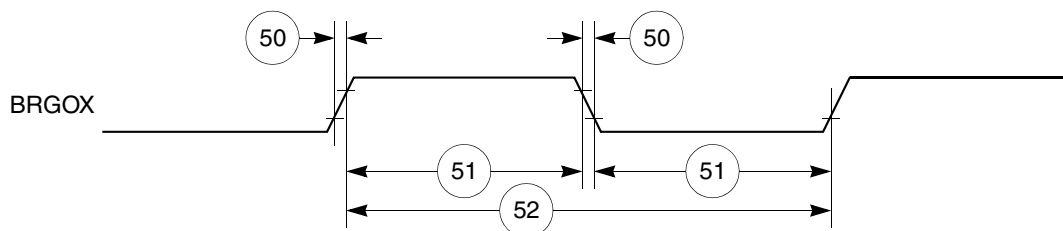


Figure 49. Baud Rate Generator Timing Diagram

11.5 Timer AC Electrical Specifications

Table 18 provides the general-purpose timer timings as shown in Figure 50.

Table 18. Timer Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
61	TIN/TGATE rise and fall time	10	—	ns
62	TIN/TGATE low time	1	—	CLK
63	TIN/TGATE high time	2	—	CLK
64	TIN/TGATE cycle time	3	—	CLK
65	CLKO low to TOUT valid	3	25	ns

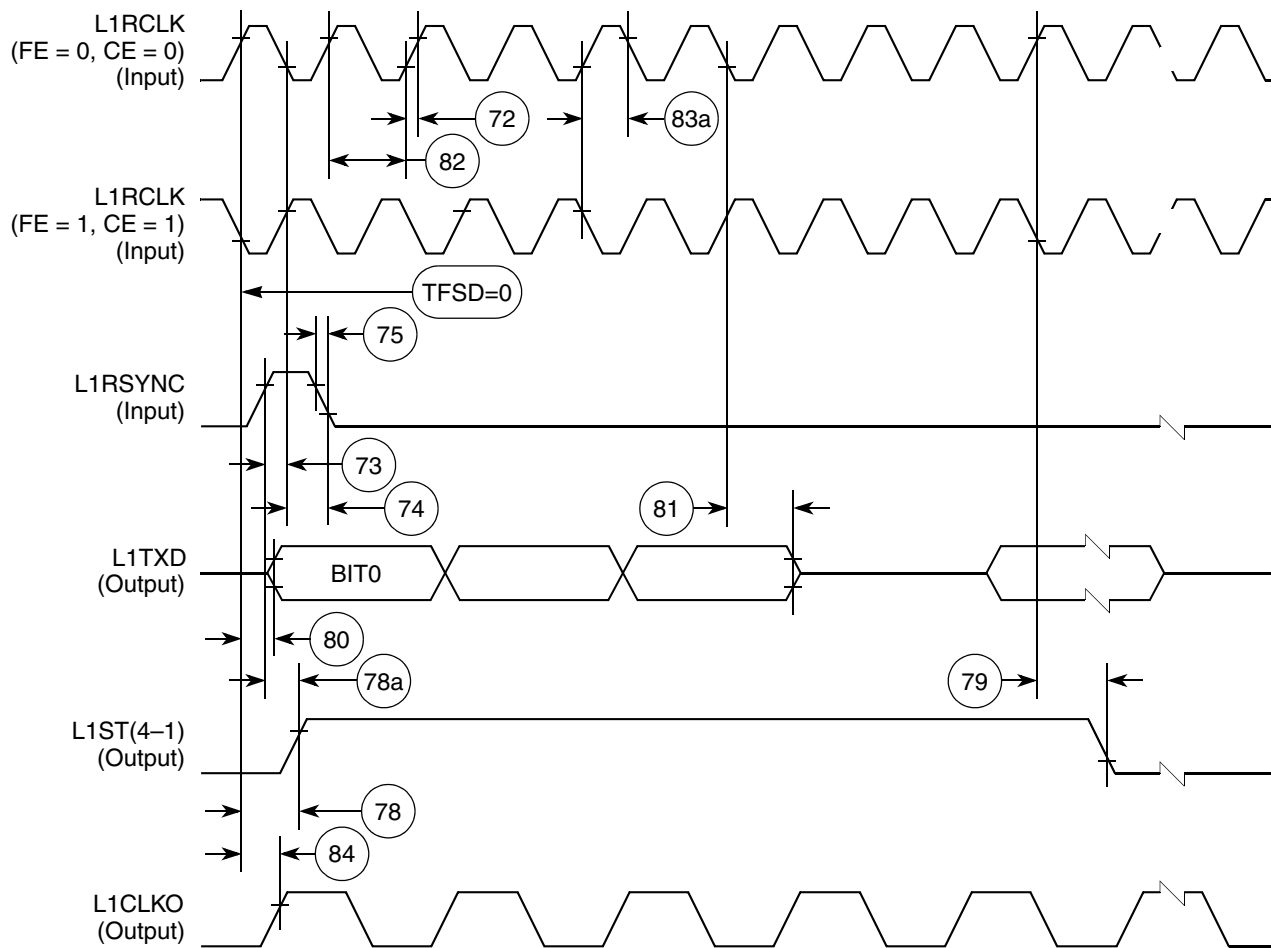


Figure 54. SI Transmit Timing with Double Speed Clocking (DSC = 1)

11.7 SCC in NMSI Mode Electrical Specifications

Table 20 provides the NMSI external clock timing.

Table 20. NMSI External Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 width high ¹	1/SYNCCLK	—	ns
101	RCLK1 and TCLK1 width low	1/SYNCCLK + 5	—	ns
102	RCLK1 and TCLK1 rise/fall time	—	15.00	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	50.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	50.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	5.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	5.00	—	ns
107	RXD1 hold time from RCLK1 rising edge ²	5.00	—	ns
108	$\overline{\text{CD1}}$ setup Time to RCLK1 rising edge	5.00	—	ns

¹ The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 2.25/1.

² Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals.

Table 21 provides the NMSI internal clock timing.

Table 21. NMSI Internal Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 frequency ¹	0.00	SYNCCLK/3	MHz
102	RCLK1 and TCLK1 rise/fall time	—	—	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	30.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	30.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	40.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	40.00	—	ns
107	RXD1 hold time from RCLK1 rising edge ²	0.00	—	ns
108	$\overline{\text{CD1}}$ setup time to RCLK1 rising edge	40.00	—	ns

¹ The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 3/1.

² Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals.

Figure 56 through Figure 58 show the NMSI timings.

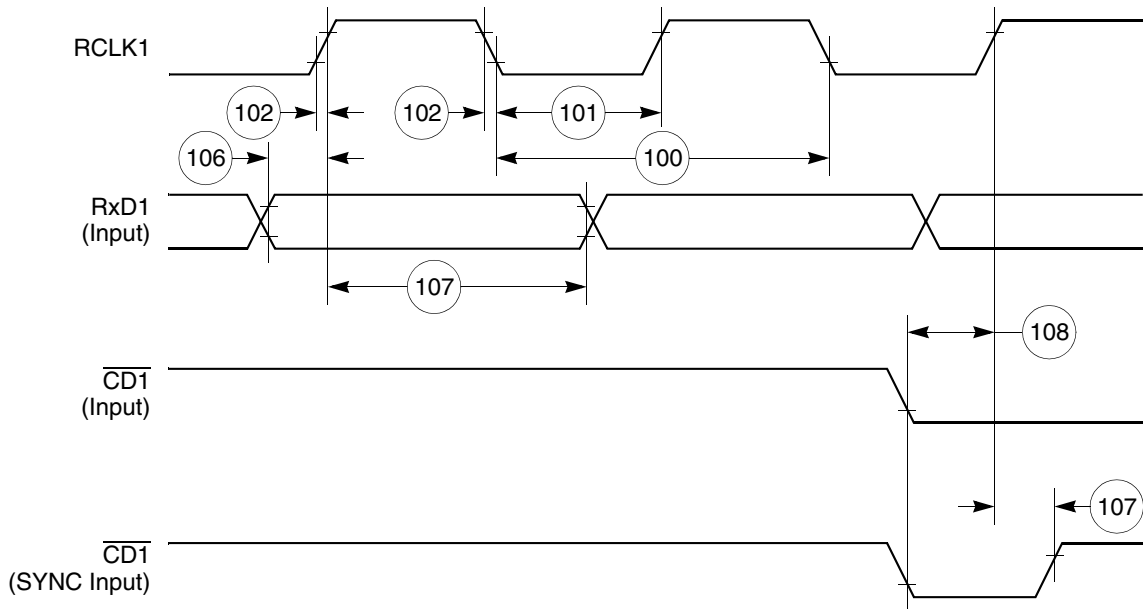


Figure 56. SCC NMSI Receive Timing Diagram

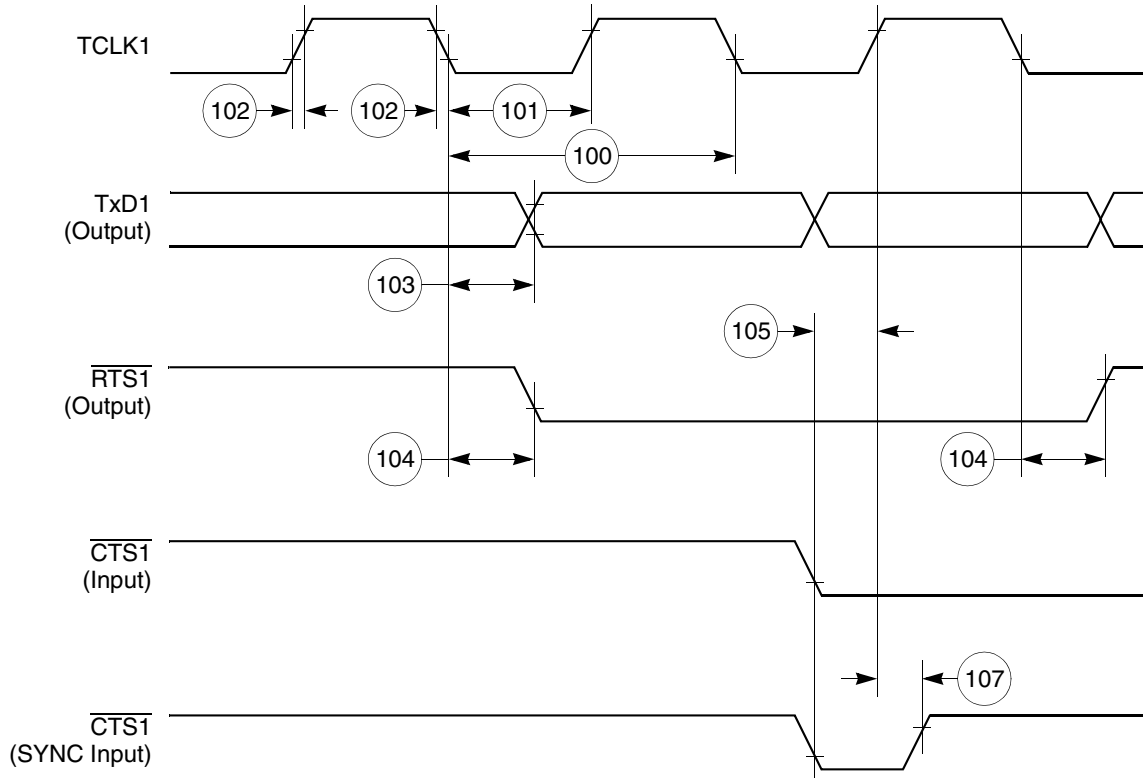


Figure 57. SCC NMSI Transmit Timing Diagram

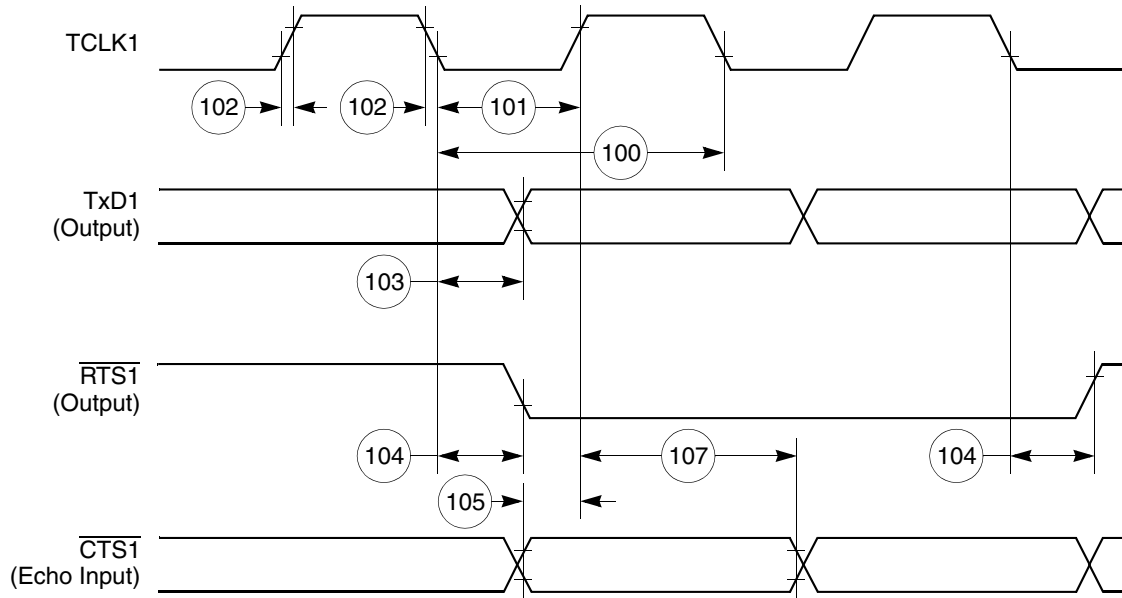


Figure 58. HDLC Bus Timing Diagram

11.8 Ethernet Electrical Specifications

Table 22 provides the Ethernet timings as shown in Figure 59 through Figure 63.

Table 22. Ethernet Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
120	CLSN width high	40	—	ns
121	RCLK1 rise/fall time	—	15	ns
122	RCLK1 width low	40	—	ns
123	RCLK1 clock period ¹	80	120	ns
124	RXD1 setup time	20	—	ns
125	RXD1 hold time	5	—	ns
126	RENA active delay (from RCLK1 rising edge of the last data bit)	10	—	ns
127	RENA width low	100	—	ns
128	TCLK1 rise/fall time	—	15	ns
129	TCLK1 width low	40	—	ns
130	TCLK1 clock period ¹	99	101	ns
131	TXD1 active delay (from TCLK1 rising edge)	10	50	ns
132	TXD1 inactive delay (from TCLK1 rising edge)	10	50	ns
133	TENA active delay (from TCLK1 rising edge)	10	50	ns
134	TENA inactive delay (from TCLK1 rising edge)	10	50	ns

Figure 69 shows the I²C bus timing.

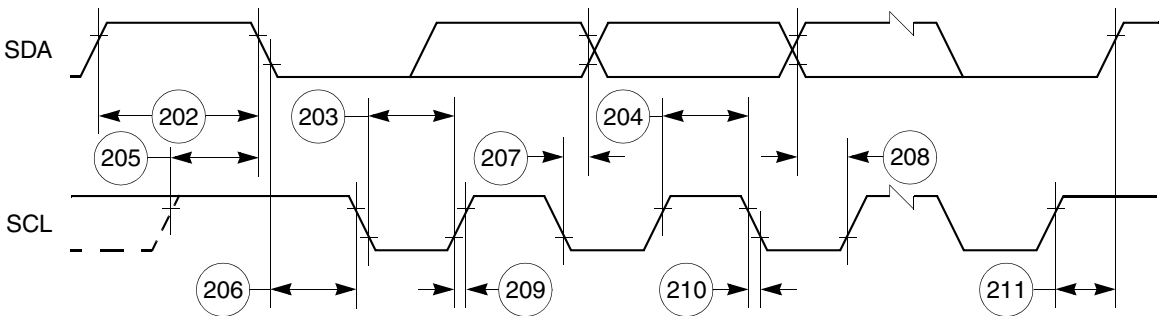


Figure 69. I²C Bus Timing Diagram

12 UTOPIA AC Electrical Specifications

Table 28 shows the AC electrical specifications for the UTOPIA interface.

Table 28. UTOPIA AC Electrical Specifications

Num	Signal Characteristic	Direction	Min	Max	Unit
U1	UtpClk rise/fall time (Internal clock option)	Output	—	3.5	ns
	Duty cycle		50	50	%
	Frequency		—	50	MHz
U1a	UtpClk rise/fall time (external clock option)	Input	—	3.5	ns
	Duty cycle		40	60	%
	Frequency		—	50	MHz
U2	$\overline{\text{RxEnb}}$ and $\overline{\text{TxEnb}}$ active delay	Output	2	16	ns
U3	UTPB, SOC, Rxclav and Txclav setup time	Input	8	—	ns
U4	UTPB, SOC, Rxclav and Txclav hold time	Input	1	—	ns
U5	UTPB, SOC active delay (and PHREQ and PHSEL active delay in MPHY mode)	Output	2	16	ns

Figure 75 shows the MII serial management channel timing diagram.

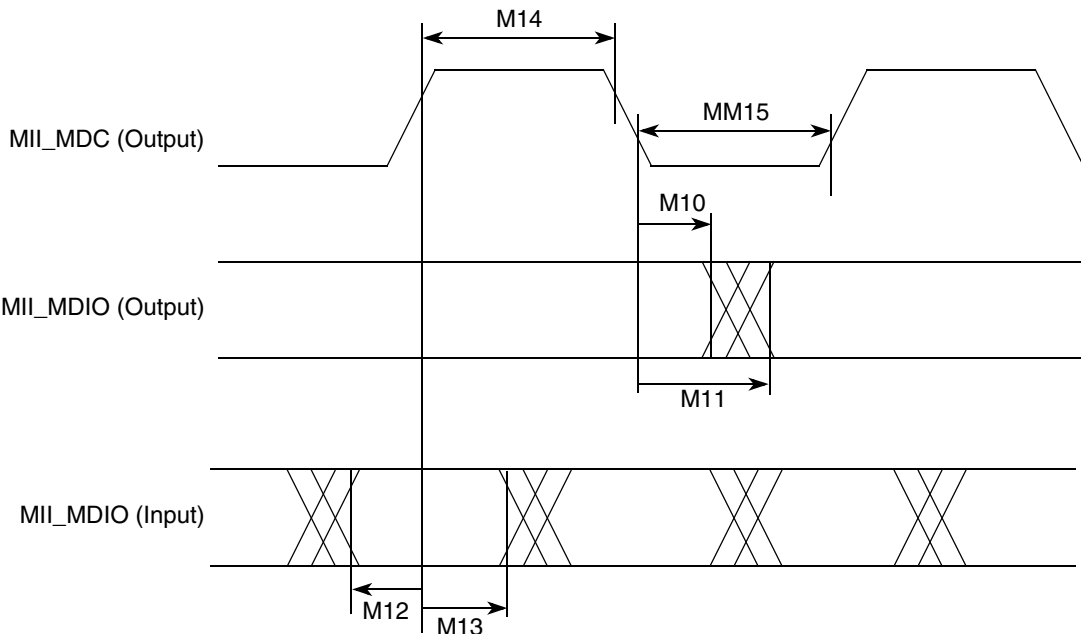


Figure 75. MII Serial Management Channel Timing Diagram

14 Mechanical Data and Ordering Information

14.1 Ordering Information

Table 33 provides information on the MPC860 Revision D.4 derivative devices.

Table 33. MPC860 Family Revision D.4 Derivatives

Device	Number of SCCs ¹	Ethernet Support ² (Mbps)	Multichannel HDLC Support	ATM Support
MPC855T	1	10/100	Yes	Yes
MPC860DE	2	10	N/A	N/A
MPC860DT		10/100	Yes	Yes
MPC860DP		10/100	Yes	Yes
MPC860EN	4	10	N/A	N/A
MPC860SR		10	Yes	Yes
MPC860T		10/100	Yes	Yes
MPC860P		10/100	Yes	Yes

¹ Serial communications controller (SCC)

² Up to 4 channels at 40 MHz or 2 channels at 25 MHz